

LMx31x Precision Voltage-to-Frequency Converters

1 Features

- Ensured Linearity 0.01% Maximum
- Improved Performance in Existing Voltage-to-Frequency Conversion Applications
- Split or Single-Supply Operation
- Operates on Single 5-V Supply
- Pulse Output Compatible With All Logic Forms
- Excellent Temperature Stability: ± 50 ppm/ $^{\circ}\text{C}$ Maximum
- Low Power Consumption: 15 mW Typical at 5 V
- Wide Dynamic Range, 100 dB Minimum at 10-kHz Full Scale Frequency
- Wide Range of Full Scale Frequency: 1 Hz to 100 kHz
- Low-Cost

2 Applications

- Voltage to Frequency Conversions
- Frequency to Voltage Conversions
- Remote-Sensor Monitoring
- Tachometers

3 Description

The LMx31 family of voltage-to-frequency converters are ideally suited for use in simple low-cost circuits for analog-to-digital conversion, precision frequency-to-voltage conversion, long-term integration, linear frequency modulation or demodulation, and many other functions. The output when used as a voltage-to-frequency converter is a pulse train at a frequency precisely proportional to the applied input voltage. Thus, it provides all the inherent advantages of the voltage-to-frequency conversion techniques, and is easy to apply in all standard voltage-to-frequency converter applications.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM231	PDIP (8)	9.81 mm $\times$ 6.35 mm
LM331		

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Schematic Diagram

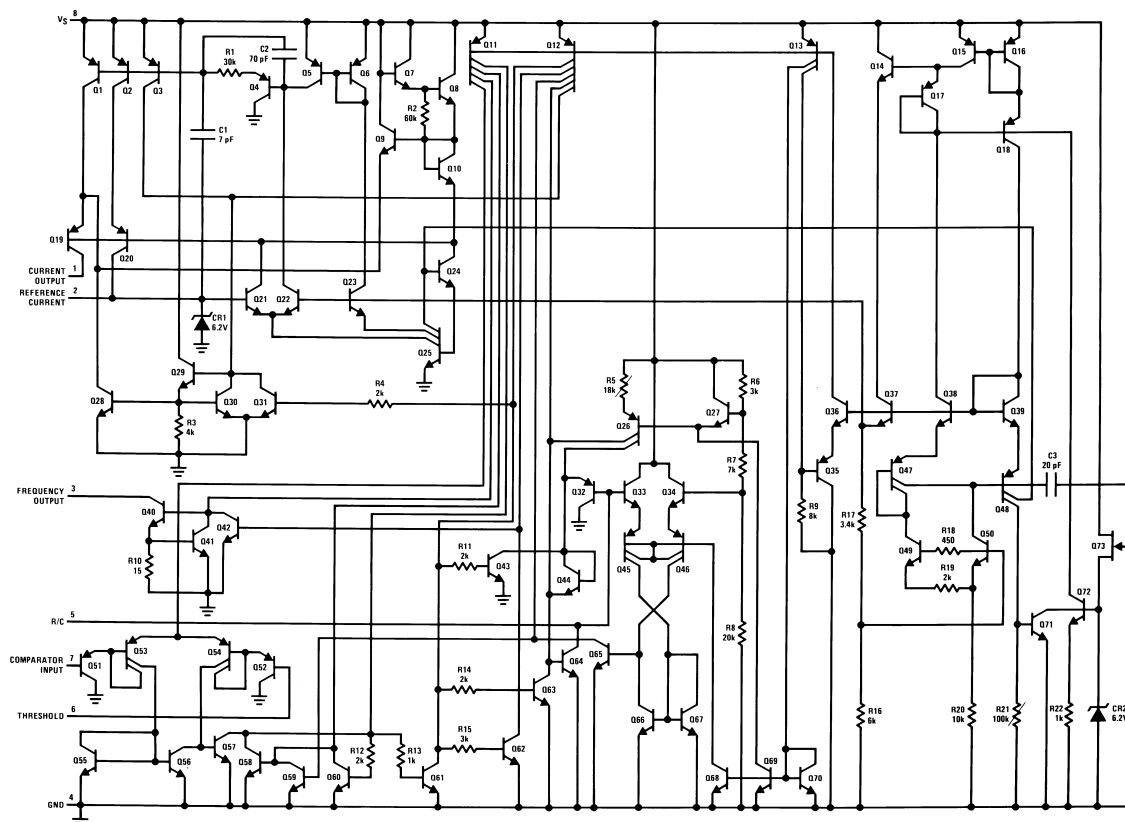


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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (March 2013) to Revision C	Page
Added <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i>, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1

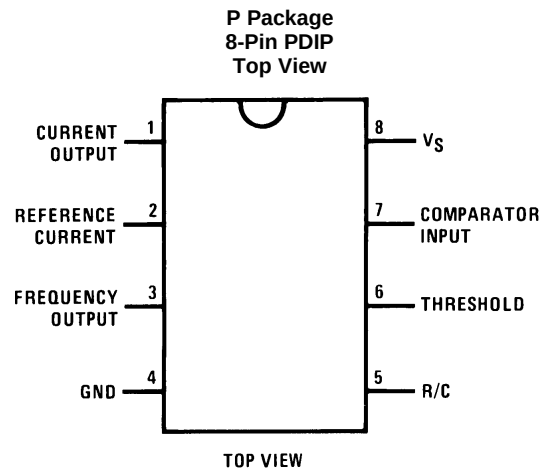
Changes from Revision A (March 2013) to Revision B	Page
Changed layout of National Data Sheet to TI format	1

5 Description continued

Further, the LMx31A attain a new high level of accuracy versus temperature which could only be attained with expensive voltage-to-frequency modules. Additionally the LMx31 are ideally suited for use in digital systems at low power supply voltages and can provide low-cost analog-to-digital conversion in microprocessor-controlled systems. And, the frequency from a battery-powered voltage-to-frequency converter can be easily channeled through a simple photo isolator to provide isolation against high common-mode levels.

The LMx31 uses a new temperature-compensated band-gap reference circuit, to provide excellent accuracy over the full operating temperature range, at power supplies as low as 4 V. The precision timer circuit has low bias currents without degrading the quick response necessary for 100-kHz voltage-to-frequency conversion. And the output are capable of driving 3 TTL loads, or a high-voltage output up to 40 V, yet is short-circuit-proof against V_{CC} .

6 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
IOUT	1	O	Current Output
IREF	2	I	Reference Current
FOUT	3	O	Frequency Output. This output is an open-collector output and requires a pullup resistor.
GND	4	G	Ground
RC	5	I	R-C filter input
THRESH	6	I	Threshold input
COMPIN	7	I	Comparator Input
VS	8	P	Supply Voltage

7 Specifications

7.1 Absolute Maximum Ratings⁽¹⁾⁽²⁾⁽³⁾

	MIN	MAX	UNIT
Supply Voltage, V_S		40	V
Output Short Circuit to Ground		Continuous	
Output Short Circuit to V_{CC}		Continuous	
Input Voltage	-0.2	+ V_S	V
Lead Temperature (Soldering, 10 sec.)	PDIP	260	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are measured with respect to GND = 0 V, unless otherwise noted.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.

7.2 ESD Ratings

	VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾⁽²⁾	±500	V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) Human body model, 100 pF discharged through a 1.5-kΩ resistor.

7.3 Recommended Operating Conditions

		MIN	MAX	UNIT
Operating Ambient Temperature	LM231, LM231A	-25	85	°C
	LM331, LM331A	0	70	°C
Supply Voltage, V_S ⁽¹⁾		4	40	V

(1) All voltages are measured with respect to GND = 0 V, unless otherwise noted.

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		LM312, LM331	UNIT
		P (PDIP)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	100	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

7.5 Electrical Characteristics

All specifications apply in the circuit of [Figure 16](#), with $4.0\text{ V} \leq V_S \leq 40\text{ V}$, $T_A = 25^\circ\text{C}$, unless otherwise specified.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
VFC Non-Linearity ⁽¹⁾		$4.5\text{ V} \leq V_S \leq 20\text{ V}$		± 0.003	± 0.01	% Full-Scale
		$T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$		± 0.006	± 0.02	% Full-Scale
VFC Non-Linearity in Circuit of Figure 14		$V_S = 15\text{ V}$, $f = 10\text{ Hz to } 11\text{ kHz}$		± 0.024	± 0.14	% Full-Scale
Conversion Accuracy Scale Factor (Gain)	LM231, LM231A	$V_{\text{IN}} = -10\text{ V}$, $R_S = 14\text{ k}\Omega$	0.95	1	1.05	kHz/V
	LM331, LM331A		0.9	1	1.1	kHz/V
Temperature Stability of Gain	LMx31	$T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$ $4.5\text{ V} \leq V_S \leq 20\text{ V}$		± 30	± 150	ppm/°C
	LMx31A			± 20	± 50	ppm/°C
Change of Gain with V_S		$4.5\text{ V} \leq V_S \leq 10\text{ V}$		0.01	0.1	%/V
		$10\text{ V} \leq V_S \leq 40\text{ V}$		0.006	0.06	%/V
Rated Full-Scale Frequency		$V_{\text{IN}} = -10\text{ V}$	10.0			kHz
Gain Stability vs. Time (1000 Hours)		$T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$		± 0.02		% Full-Scale
Over Range (Beyond Full-Scale) Frequency		$V_{\text{IN}} = -11\text{ V}$	10%			
INPUT COMPARATOR						
Offset Voltage				± 3	± 10	mV
LM231/LM331		$T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$		± 4	± 14	mV
LM231A/LM331A		$T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$		± 3	± 10	mV
Bias Current				-80	-300	nA
Offset Current				± 8	± 100	nA
Common-Mode Range		$T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$	-0.2		$V_{\text{CC}} - 2$	V
TIMER						
Timer Threshold Voltage, Pin 5			$0.63 \times V_S$	$0.667 \times V_S$	$0.7 \times V_S$	
Input Bias Current, Pin 5		$V_S = 15\text{ V}$				
All Devices		$0\text{ V} \leq V_{\text{PIN } 5} \leq 9.9\text{ V}$		± 10	± 100	nA
LM231/LM331		$V_{\text{PIN } 5} = 10\text{ V}$		200	1000	nA
LM231A/LM331A		$V_{\text{PIN } 5} = 10\text{ V}$		200	500	nA
$V_{\text{SAT PIN } 5}$ (Reset)		$I = 5\text{ mA}$		0.22	0.5	V

(1) Non-linearity is defined as the deviation of f_{OUT} from $V_{\text{IN}} \times (10\text{ kHz}/-10\text{ V}_{\text{DC}})$ when the circuit has been trimmed for zero error at 10 Hz and at 10 kHz, over the frequency range 1 Hz to 11 kHz. For the timing capacitor, C_T , use NPO ceramic, Teflon®, or polystyrene.

Electrical Characteristics (continued)

All specifications apply in the circuit of [Figure 16](#), with $4.0\text{ V} \leq V_S \leq 40\text{ V}$, $T_A = 25^\circ\text{C}$, unless otherwise specified.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
CURRENT SOURCE (PIN 1)						
Output Current	LM231, LM231A	$R_S = 14\text{ k}\Omega$, $V_{\text{PIN } 1} = 0$	126	135	144	μA
	LM331, LM331A		116	136	156	μA
Change with Voltage		$0\text{V} \leq V_{\text{PIN } 1} \leq 10\text{ V}$		0.2	1	μA
Current Source OFF Leakage	LM231, LM231A, LM331, LM331A			0.02	10	nA
	All Devices	$T_A = T_{\text{MAX}}$		2	50	nA
Operating Range of Current (Typical)			(10 to 500)			μA
REFERENCE VOLTAGE (PIN 2)						
LM231, LM231A			1.76	1.89	2.02	V_{DC}
LM331, LM331A			1.7	1.89	2.08	V_{DC}
Stability vs. Temperature				± 60		ppm/ $^{\circ}\text{C}$
Stability vs. Time, 1000 Hours				$\pm 0.1\%$		
LOGIC OUTPUT (PIN 3)						
V_{SAT}	$I = 5\text{ mA}$			0.15	0.5	V
	$I = 3.2\text{ mA}$ (2 TTL Loads), $T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$			0.1	0.4	V
OFF Leakage				± 0.05	1	μA
SUPPLY CURRENT						
LM231, LM231A		$V_S = 5\text{ V}$	2	3	4	mA
		$V_S = 40\text{ V}$	2.5	4	6	mA
LM331, LM331A		$V_S = 5\text{ V}$	1.5	3	6	mA
		$V_S = 40\text{ V}$	2	4	8	mA

7.6 Dissipation Ratings

	VALUE	UNIT
Package Dissipation at 25°C ⁽¹⁾	1.25	W

- (1) The absolute maximum junction temperature (T_{Jmax}) for this device is 150°C . The maximum allowable power dissipation is dictated by T_{Jmax} , the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature T_A , and can be calculated using the formula $P_{\text{Dmax}} = (T_{\text{Jmax}} - T_A) / \theta_{\text{JA}}$. The values for maximum power dissipation will be reached only when the device is operated in a severe fault condition (e.g., when input or output pins are driven beyond the power supply voltages, or the power supply polarity is reversed). Obviously, such conditions should always be avoided.

7.7 Typical Characteristics

(All electrical characteristics apply for the circuit of [Figure 16](#), unless otherwise noted.)

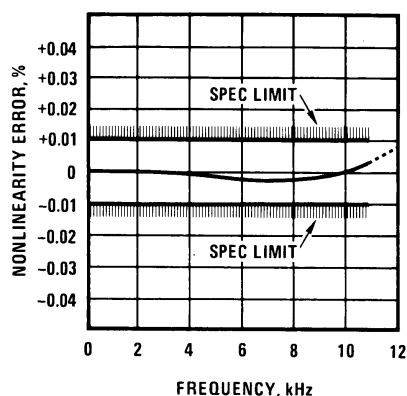


Figure 1. Non-Linearity Error as Precision V-to-F Converter
([Figure 16](#))

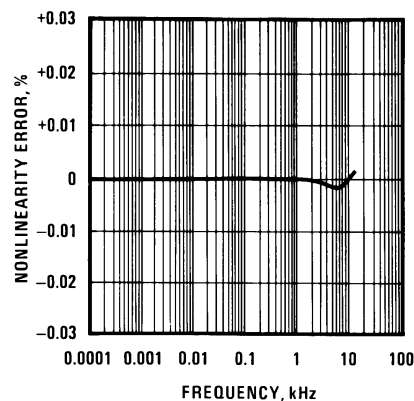


Figure 2. Non-Linearity Error

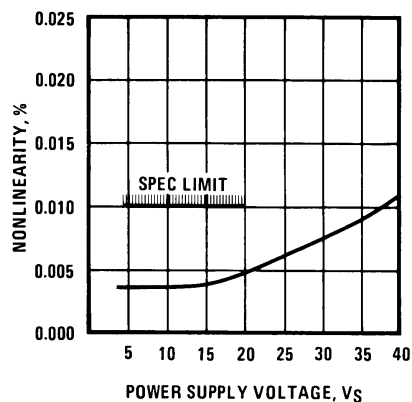


Figure 3. Non-Linearity Error vs. Power Supply Voltage

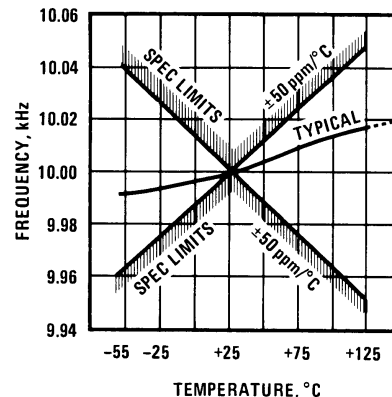


Figure 4. Frequency vs. Temperature

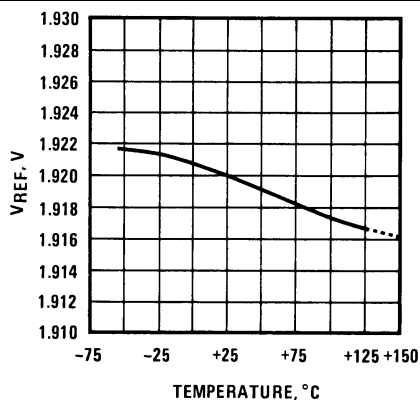


Figure 5. V_{REF} vs. Temperature

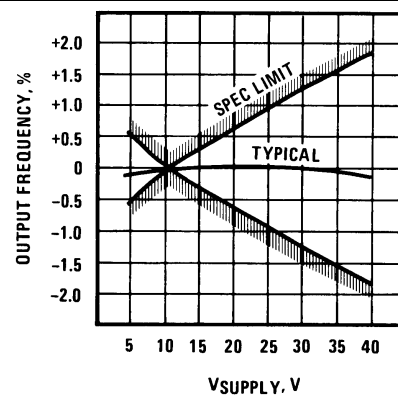


Figure 6. Output Frequency vs. V_{SUPPLY}

Typical Characteristics (continued)

(All electrical characteristics apply for the circuit of [Figure 16](#), unless otherwise noted.)

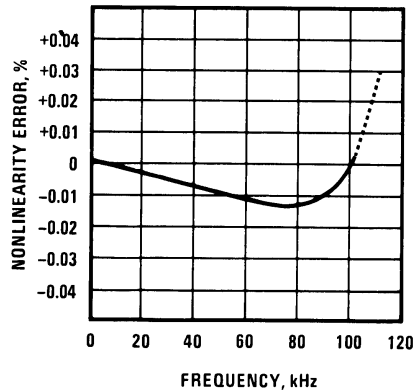


Figure 7. 100 kHz Non-Linearity Error ([Figure 17](#))

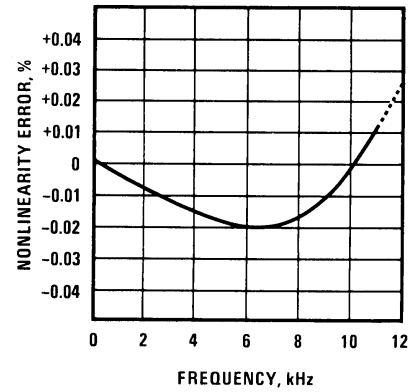


Figure 8. Non-Linearity Error ([Figure 14](#))

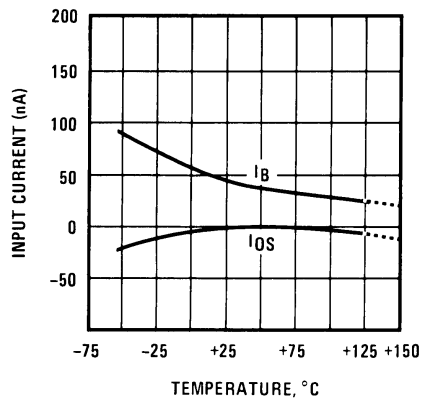


Figure 9. Input Current (Pins 6,7) vs. Temperature

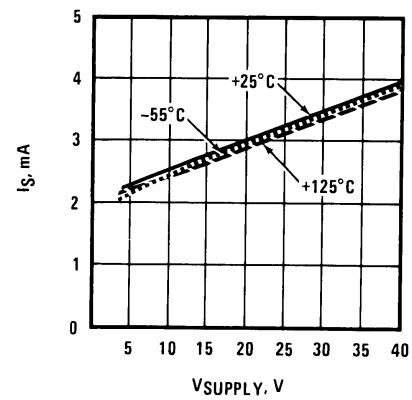


Figure 10. Power Drain vs. V_{SUPPLY}

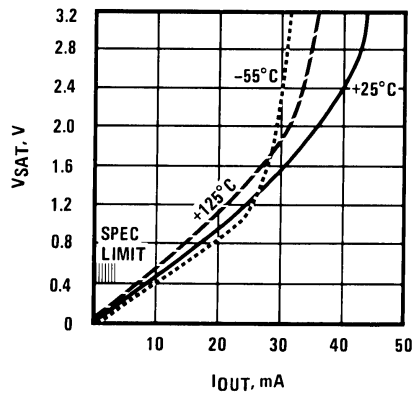


Figure 11. Output Saturation Voltage vs. I_{OUT} (Pin 3)

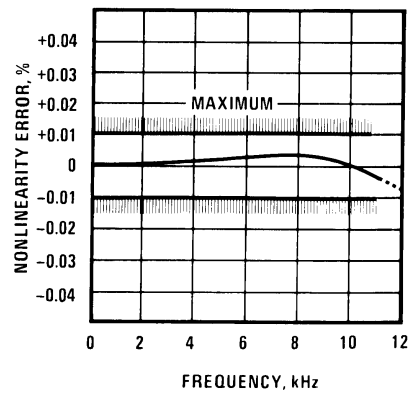


Figure 12. Non-Linearity Error, Precision F-to-V Converter ([Figure 19](#))

8 Detailed Description

8.1 Overview

8.1.1 Detail of Operation, Functional Block Diagram

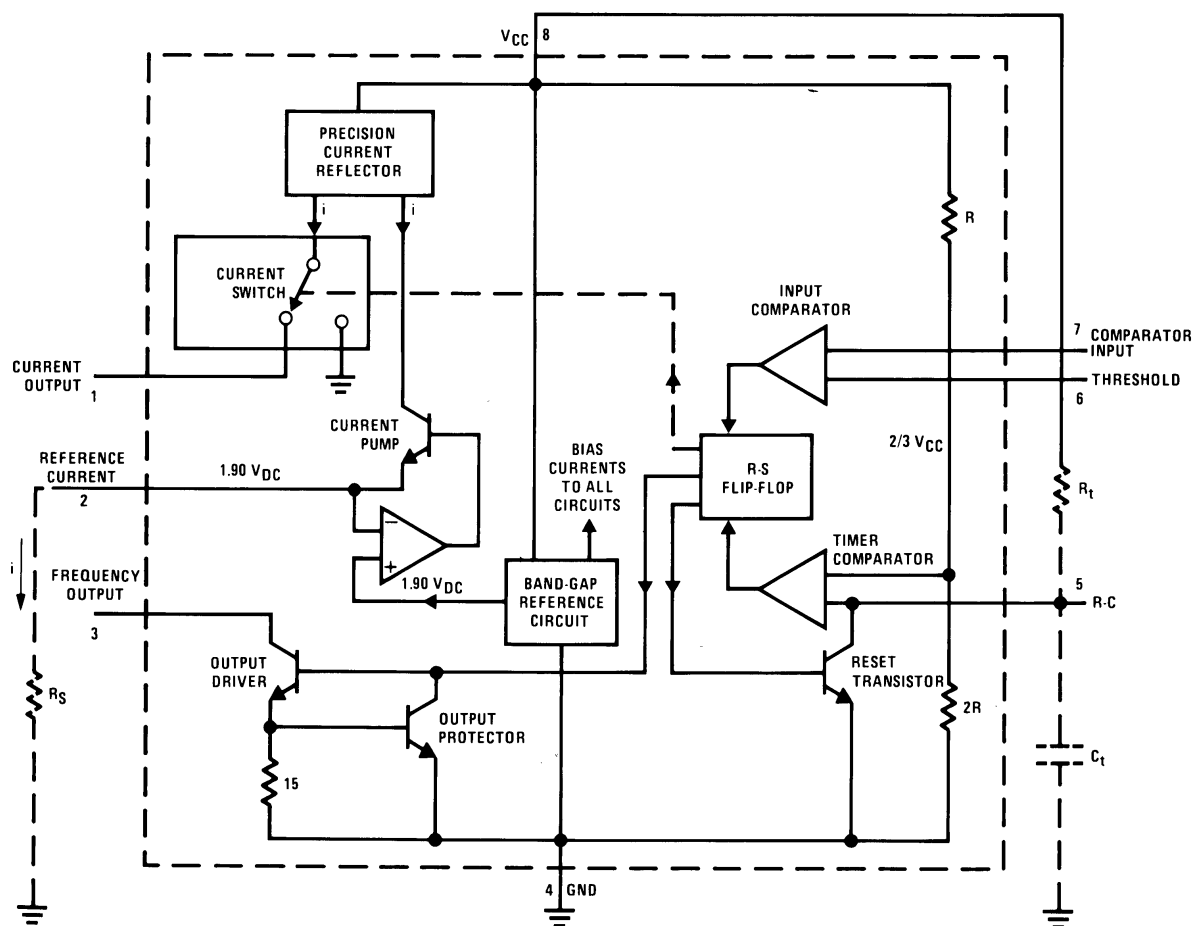
The [Functional Block Diagram](#) shows a band gap reference which provides a stable 1.9-V_{DC} output. This 1.9 V_{DC} is well regulated over a V_{S} range of 3.9 V to 40 V . It also has a flat, low temperature coefficient, and typically changes less than $\frac{1}{2}\%$ over a 100°C temperature change.

The current pump circuit forces the voltage at pin 2 to be at 1.9 V , and causes a current $i = 1.90\text{ V}/R_{\text{S}}$ to flow. For $R_{\text{S}}=14\text{ k}$, $i=135\text{ }\mu\text{A}$. The precision current reflector provides a current equal to i to the current switch. The current switch switches the current to pin 1 or to ground, depending upon the state of the R-S flip-flop.

The timing function consists of an R-S flip-flop and a timer comparator connected to the external $R_{\text{T}}C_{\text{T}}$ network. When the input comparator detects a voltage at pin 7 higher than pin 6, it sets the R-S flip-flop which turns ON the current switch and the output driver transistor. When the voltage at pin 5 rises to $\frac{2}{3}V_{\text{CC}}$, the timer comparator causes the R-S flip-flop to reset. The reset transistor is then turned ON and the current switch is turned OFF.

However, if the input comparator still detects the voltage on pin 7 as higher than pin 6 when pin 5 crosses $\frac{2}{3}V_{\text{CC}}$, the flip-flop will not be reset, and the current at pin 1 will continue to flow, trying to make the voltage at pin 6 higher than pin 7. This condition will usually apply under start-up conditions or in the case of an overload voltage at signal input. During this sort of overload the output frequency will be 0. As soon as the signal is restored to the working range, the output frequency will be resumed.

8.2 Functional Block Diagram



8.3 Feature Description

The LMx31 operate over a wide voltage range of 4 V to 40 V.

The voltage at pin 2 is regulated at $1.90 V_{DC}$ for all values of i between 10 μA to 500 μA . It can be used as a voltage reference for other components, but take care to ensure that current is not taken from it which could reduce the accuracy of the converter.

8.4 Device Functional Modes

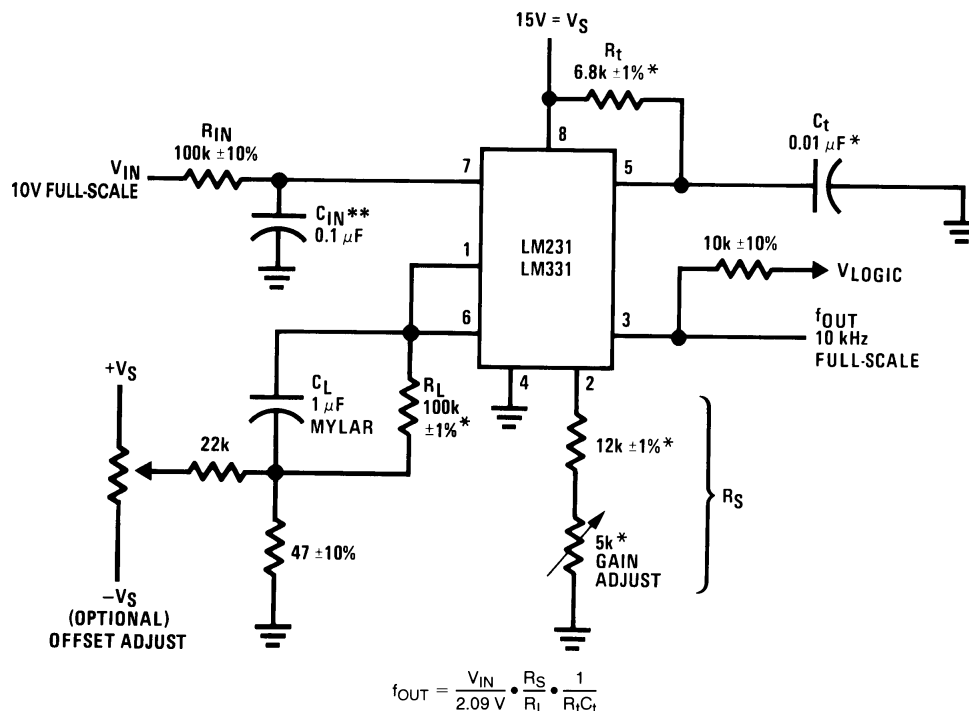
The output driver transistor acts to saturate pin 3 with an ON resistance of about 50 Ω . In case of overvoltage, the output current is actively limited to less than 50 mA.

If the voltage on pin 7 is higher than pin 6 when pin 5 crosses $\frac{2}{3} V_{CC}$, the LMx31 internal flip-flop will not be reset, and the current at pin 1 will continue to flow, trying to make the voltage at pin 6 higher than pin 7. This condition will usually apply under start-up conditions or in the case of an overload voltage at signal input. During this sort of overload the output frequency will be 0. As soon as the signal is restored to the working range, the output frequency will be resumed.

9.2 Typical Applications

9.2.1 Basic Voltage-to-Frequency Converter

The simple stand-alone V-to-F converter shown in Figure 14 includes all the basic circuitry of Figure 13 plus a few components for improved performance.



*Use stable components with low temperature coefficients. See [Application Information](#).

**0.1 μF or 1 μF, See [Typical Applications](#).

Figure 14. Simple Stand-Alone V-to-F Converter with ±0.03% Typical Linearity (f = 10 Hz to 11 kHz)

9.2.1.1 Design Requirements

For this example, the system requirements are 0.05% linearity over an output frequency range of 10 Hz to 4 kHz with an input voltage range of 25 mV to 12.5 V. The available supply voltage is 15.0 V.

9.2.1.2 Detailed Design Procedure

A capacitor C_{IN} is added from pin 7 to ground to act as a filter for V_{IN} , use of a 0.1 μF is appropriate for this application. A value of 0.01 μF to 0.1 μF will be adequate in most cases; however, in cases where better filtering is required, a 1-μF capacitor can be used. When the RC time constants are matched at pin 6 and pin 7, a voltage step at V_{IN} will cause a step change in f_{OUT} . If C_{IN} is much less than C_L , a step at V_{IN} may cause f_{OUT} to stop momentarily.

Next, we cancel the comparator bias current by setting R_{IN} to 100 kΩ to match R_L . This will help to minimize any frequency offset.

For best results, all the components should be stable low-temperature-coefficient components, such as metal-film resistors. The capacitor should have low dielectric absorption; depending on the temperature characteristics desired, NPO ceramic, polystyrene, Teflon or polypropylene are best suited.

The resistance R_S at pin 2 is made up of a 12-kΩ fixed resistor plus a 5-kΩ (cermet, preferably) gain adjust rheostat. The function of this adjustment is to trim out the gain tolerance of the LMx31, and the tolerance of R_T , R_L and C_T .

Typical Applications (continued)

A 47-Ω resistor in series with the 1-μF capacitor (CL) provides hysteresis, which helps the input comparator provide the excellent linearity.

This results in the transfer function of $f_{OUT} = (V_{IN} / 2.09 \text{ V}) \times (R_S / R_L) \times (1 / R_t C_t)$.

9.2.1.3 Application Curve

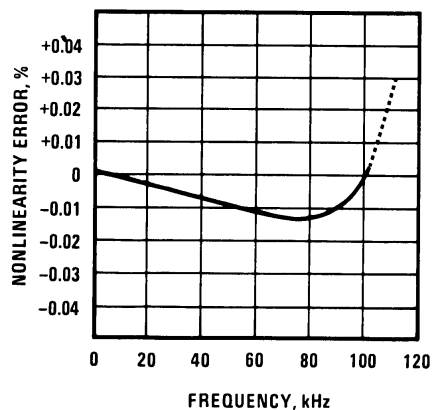


Figure 15. Output Non-Linearity Error vs. Frequency

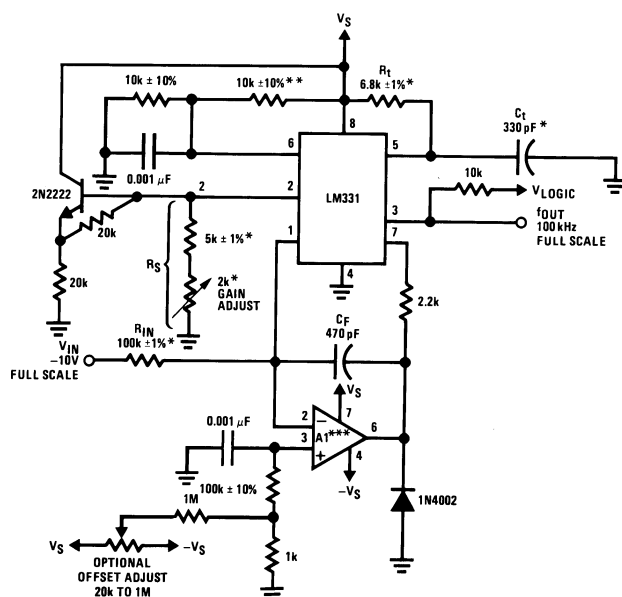
9.3 System Examples

9.3.1 F-to-V Converters

In these applications, a pulse input at f_{IN} is differentiated by a C-R network and the negative-going edge at pin 6 causes the input comparator to trigger the timer circuit. Just as with a V-to-F converter, the average current flowing out of pin 1 is $I_{AVERAGE} = i \times (1.1 R_T C_T) \times f$.

In the simple circuit of Figure 18, this current is filtered in the network $R_L = 100\text{ k}\Omega$ and $1\text{ }\mu\text{F}$. The ripple will be less than 10-mV peak, but the response will be slow, with a 0.1 second time constant, and settling of 0.7 second to 0.1% accuracy.

In the precision circuit, an operational amplifier provides a buffered output and also acts as a 2-pole filter. The ripple will be less than 5-mV peak for all frequencies above 1 kHz, and the response time will be much quicker than in Figure 18. However, for input frequencies below 200 Hz, this circuit will have worse ripple than Figure 18. The engineering of the filter time-constants to get adequate response and small enough ripple simply requires a study of the compromises to be made. Inherently, V-to-F converter response can be fast, but F-to-V response can not.



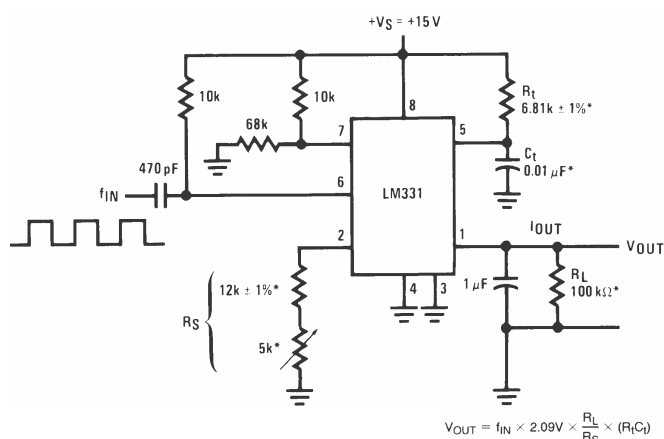
100 kHz Full-Scale, $\pm 0.03\%$ Non-Linearity

*Use stable components with low temperature coefficients.

**This resistor can be 5 k Ω or 10 k Ω for $V_S=8\text{V}$ to 22V, but must be 10 k Ω for $V_S=4.5\text{V}$ to 8V.

***Use low offset voltage and low offset current op-amps for A1: recommended types LF411A or LF356.

Figure 17. Precision Voltage-to-Frequency Converter

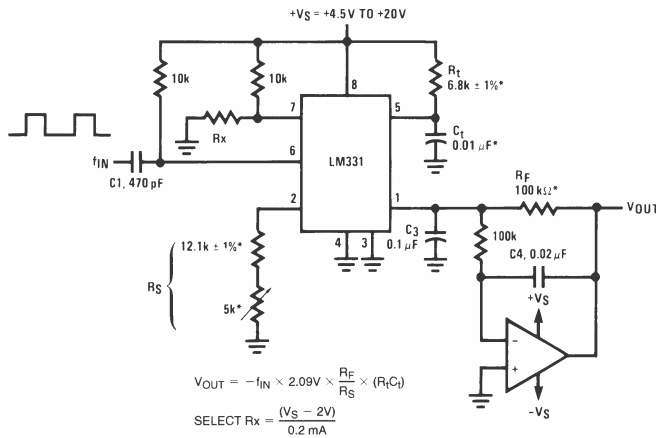


10 kHz Full-Scale, $\pm 0.06\%$ Non-Linearity

*Use stable components with low temperature coefficients.

Figure 18. Simple Frequency-to-Voltage Converter

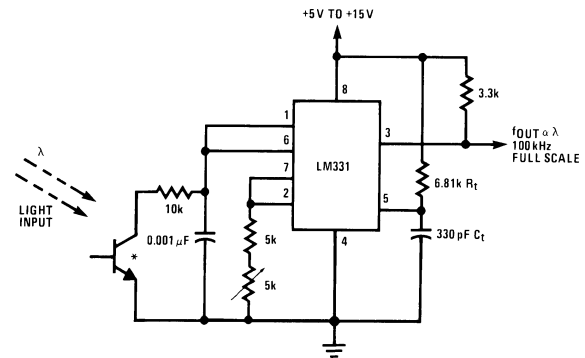
System Examples (continued)



10 kHz Full-Scale With 2-Pole Filter, $\pm 0.01\%$ Non-Linearity Maximum

*Use stable components with low temperature coefficients.

Figure 19. Precision Frequency-to-Voltage Converter,



*L14F-1, L14G-1 or L14H-1, photo transistor (General Electric Co.) or similar

Figure 20. Light Intensity to Frequency Converter

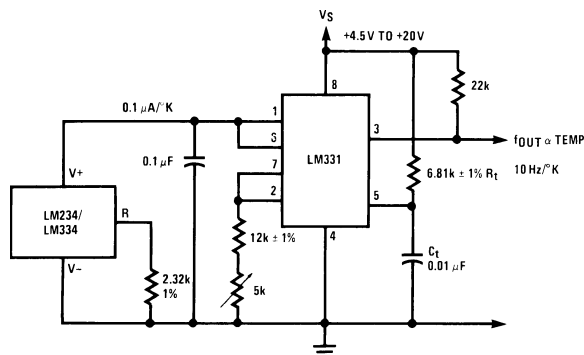


Figure 21. Temperature to Frequency Converter

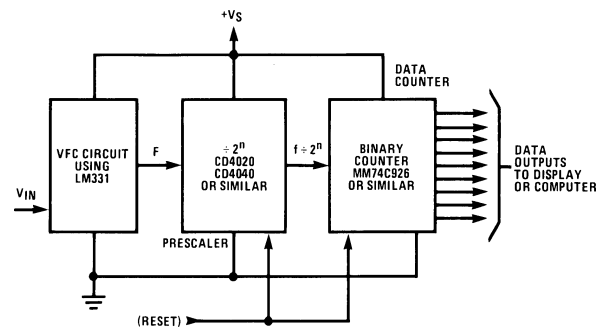


Figure 22. Long-Term Digital Integrator Using VFC

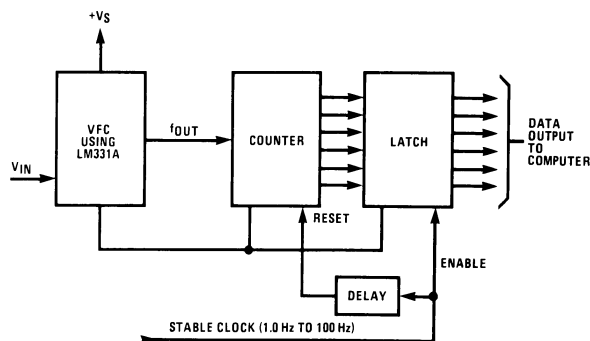


Figure 23. Basic Analog-to-Digital Converter Using Voltage-to-Frequency Converter

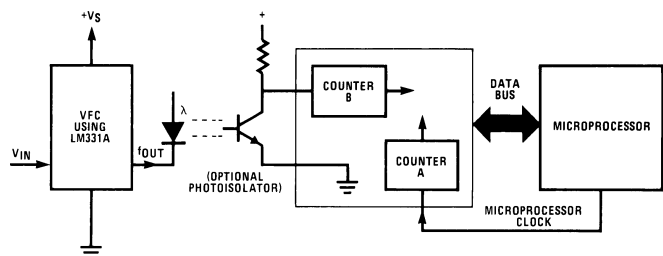


Figure 24. Analog-to-Digital Converter With Microprocessor

System Examples (continued)

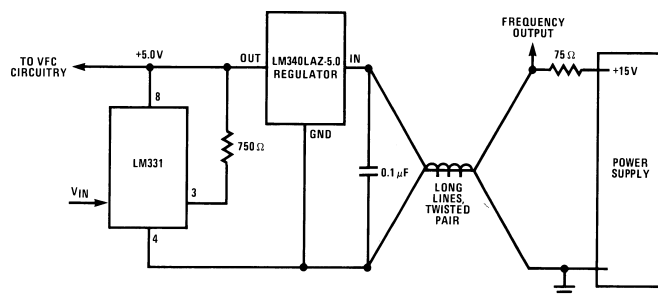


Figure 25. Remote Voltage-to-Frequency Converter With 2-Wire Transmitter and Receiver

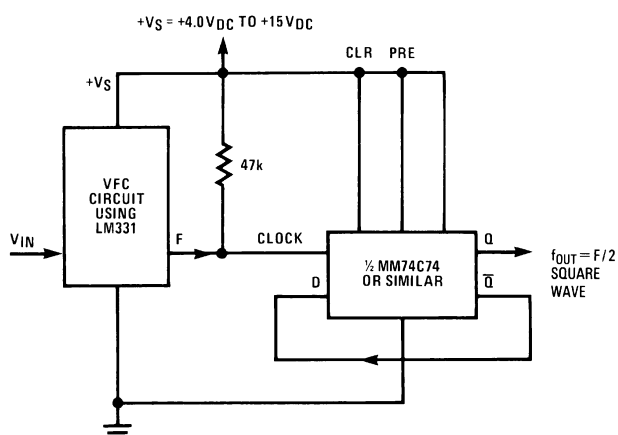


Figure 26. Voltage-to-Frequency Converter With Square-Wave Output Using $\div 2$ Flip-Flop

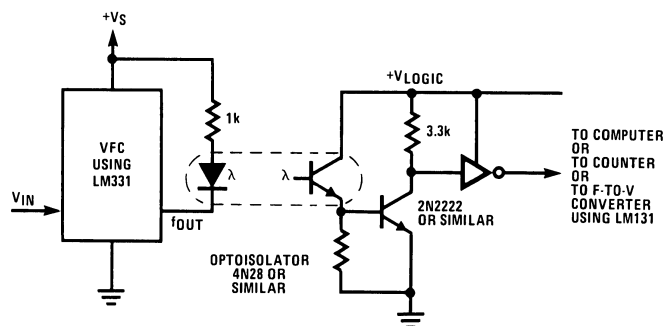


Figure 27. Voltage-to-Frequency Converter With Isolators

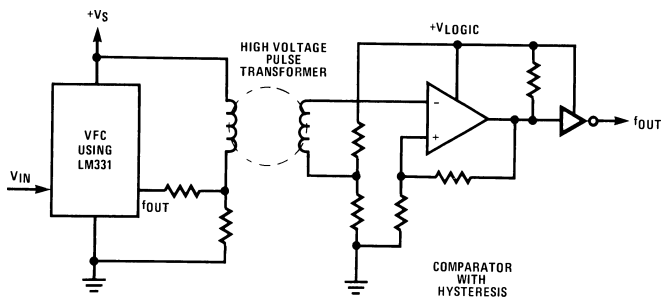


Figure 28. Voltage-to-Frequency Converter With Isolators

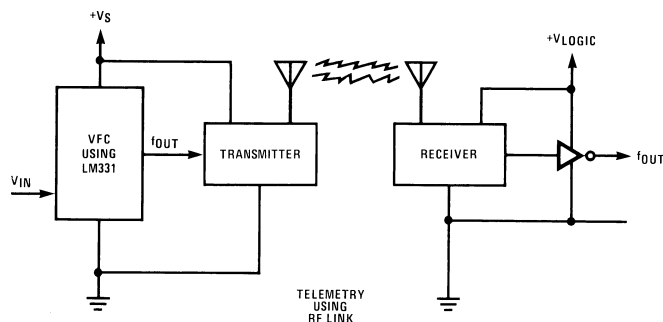


Figure 29. Voltage-to-Frequency Converter With Isolators

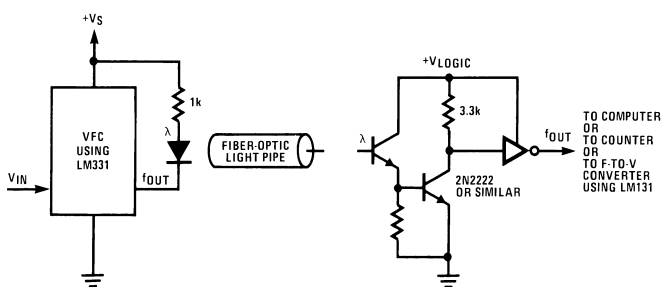


Figure 30. Voltage-to-Frequency Converter With Isolators

10 Power Supply Recommendations

The LMx31 can operate over a wide supply voltage range of 4 V to 40 V. For proper operation, the supply pin should be bypassing to ground with a low-ESR, 1- μ F capacitor. It is acceptable to use X7R capacitors for this. For systems using higher supply voltages, ensure that the voltage rating for the bypass caps is sufficient.

11 Layout

11.1 Layout Guidelines

Bypass capacitors must be placed as close as possible to the supply pin. As the LM331 is a through-hole device, it is acceptable to place the bypass capacitor on the bottom layer.

If an input capacitor to ground is used to clean the input signal, the capacitor should be placed close to the supply pin.

Use of a ground plane is recommended to provide a low-impedance ground across the circuit.

11.2 Layout Example

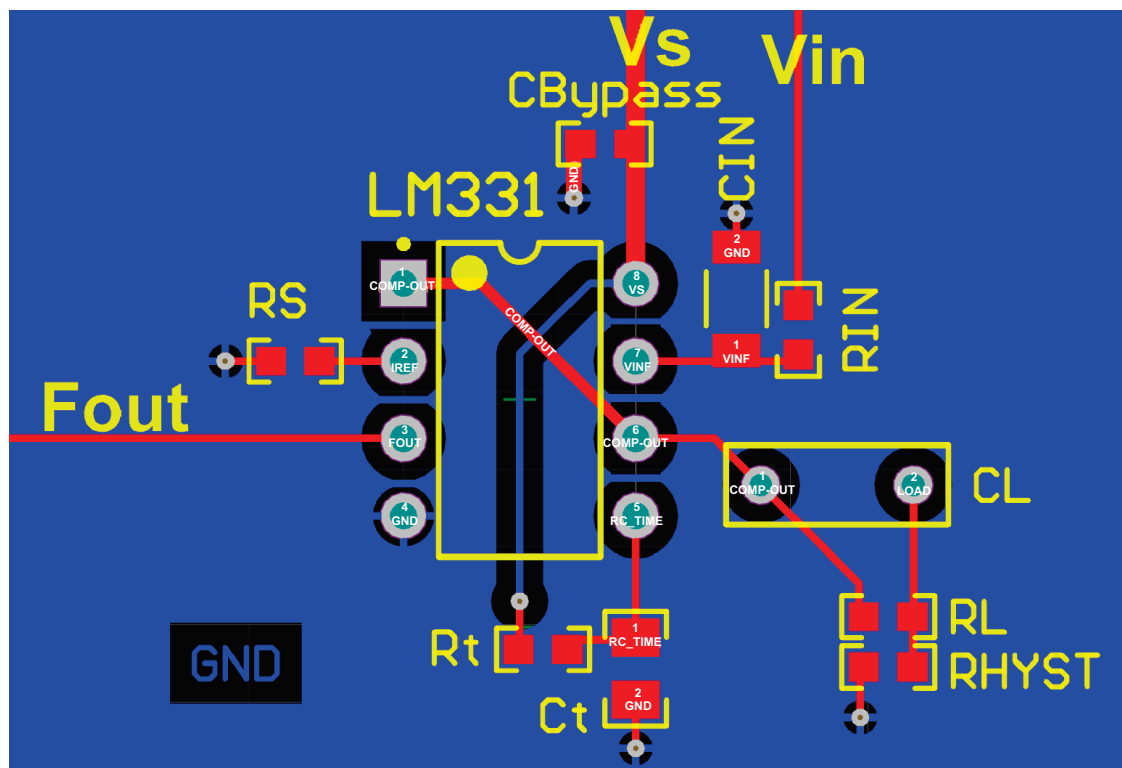


Figure 31. Layout Example

12 Device and Documentation Support

12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LM231	Click here	Click here	Click here	Click here	Click here
LM331	Click here	Click here	Click here	Click here	Click here

12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks

E2E is a trademark of Texas Instruments.

Teflon is a registered trademark of E.

All other trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM231AN/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-25 to 85	LM 231AN	Samples
LM231N/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-25 to 85	LM 231N	Samples
LM331AN/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM		LM 331AN	Samples
LM331N/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM 331N	Samples
RC4151NB	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI	0 to 70	LM 331N	
RV4151NB	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI	-25 to 85	LM 231N	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

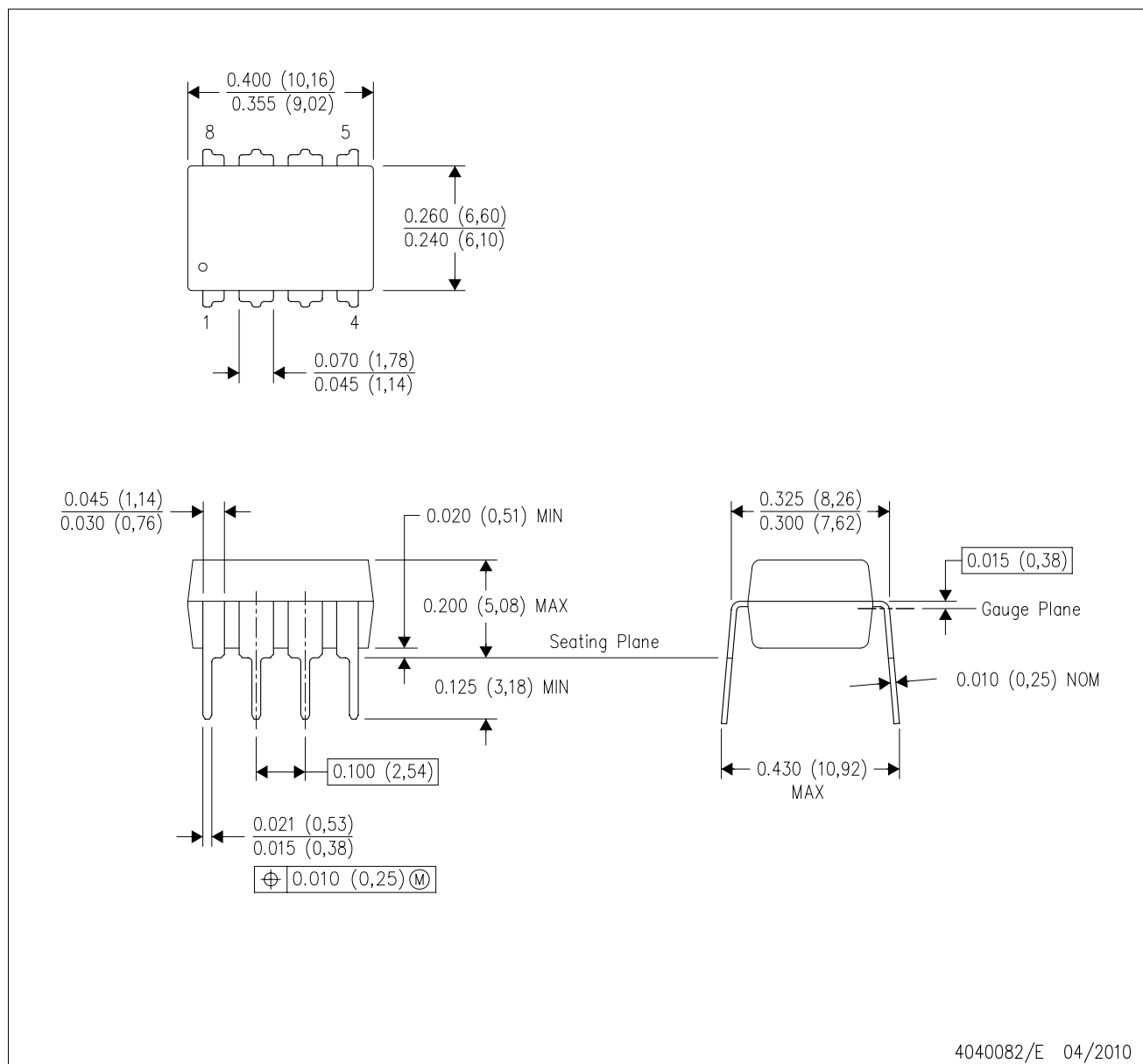
⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

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